Microchip Technology - DSPIC33EP32MC502-E/SS Datasheet

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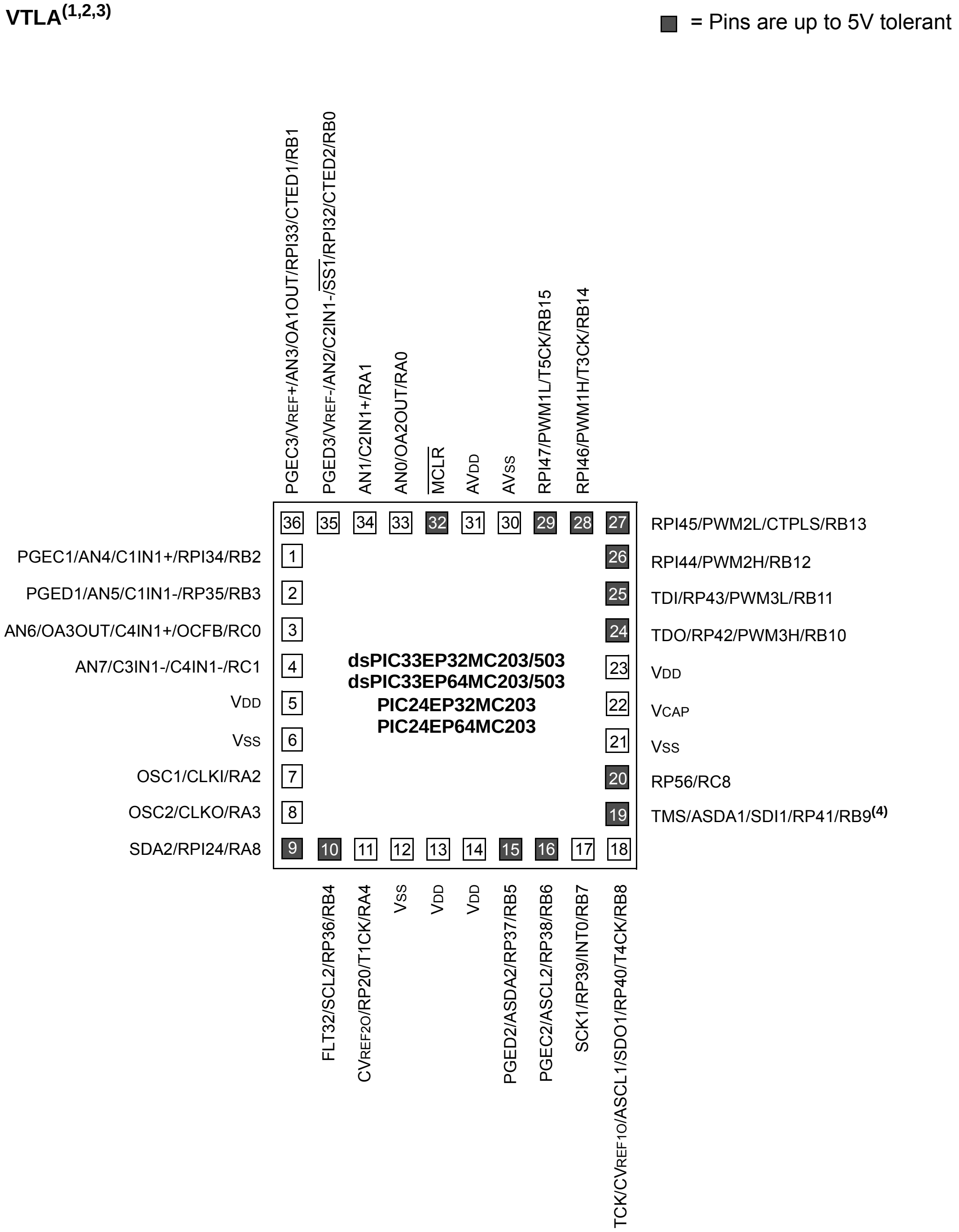
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (10.7K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32mc502-e-ss

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS AND MICROCONTROLLERS

> **Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com)
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All V_{DD} and V_{SS} pins (see **Section 2.2 "Decoupling Capacitors"**)
- All AV_{DD} and AV_{SS} pins (regardless if ADC module is not used) (see **Section 2.2 "Decoupling Capacitors"**)
- V_{CAP} (see **Section 2.3 "CPU Logic Filter Capacitor Connection (V_{CAP})"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- $V_{REF}+/V_{REF}-$ pins are used when external voltage reference for the ADC module is implemented

> **Note:** The AV_{DD} and AV_{SS} pins must be connected, independent of the ADC voltage reference source.

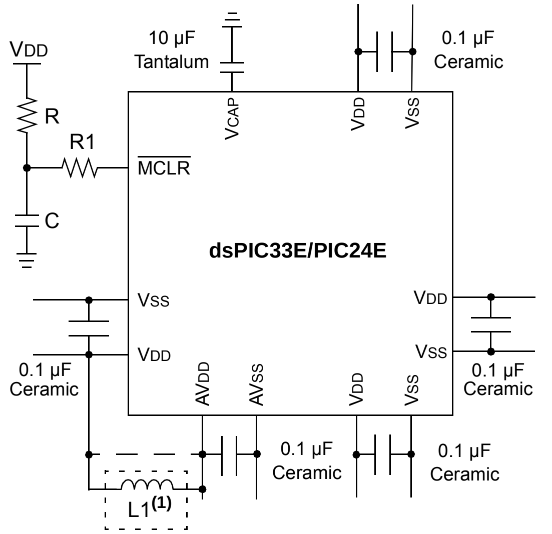
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as V_{DD}, V_{SS}, AV_{DD} and AV_{SS} is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 1 Ohm) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD and must have a capacitor greater than 4.7 µF (10 µF is recommended), 16V connected to ground. The type can be ceramic or tantalum. See **Section 30.0 “Electrical Characteristics”** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length not exceeds one-quarter inch (6 mm). See **Section 27.3 “On-Chip Voltage Regulator”** for details.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions:

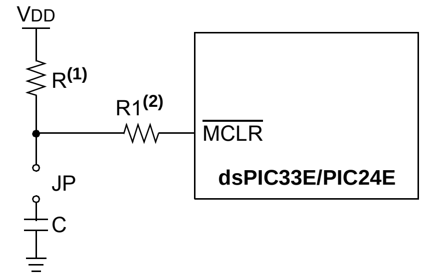
- Device Reset
- Device Programming and Debugging.

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor, C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met.

FIGURE 2-5: SINGLE-PHASE SYNCHRONOUS BUCK CONVERTER

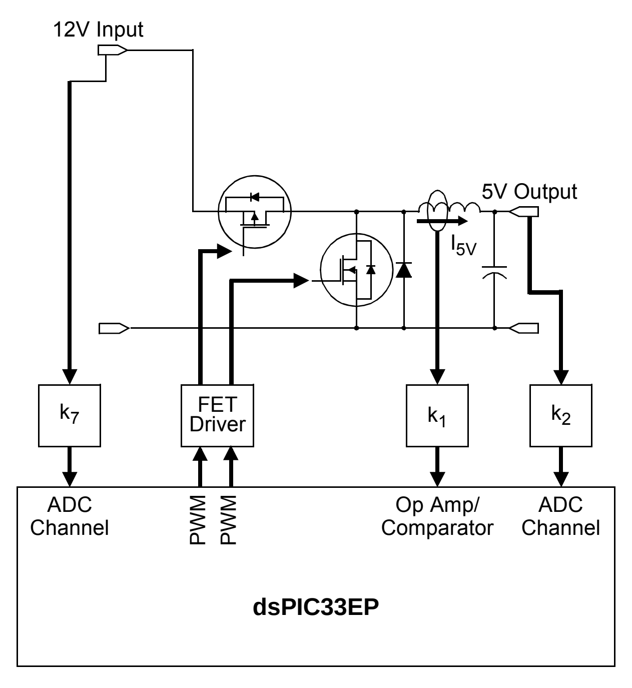
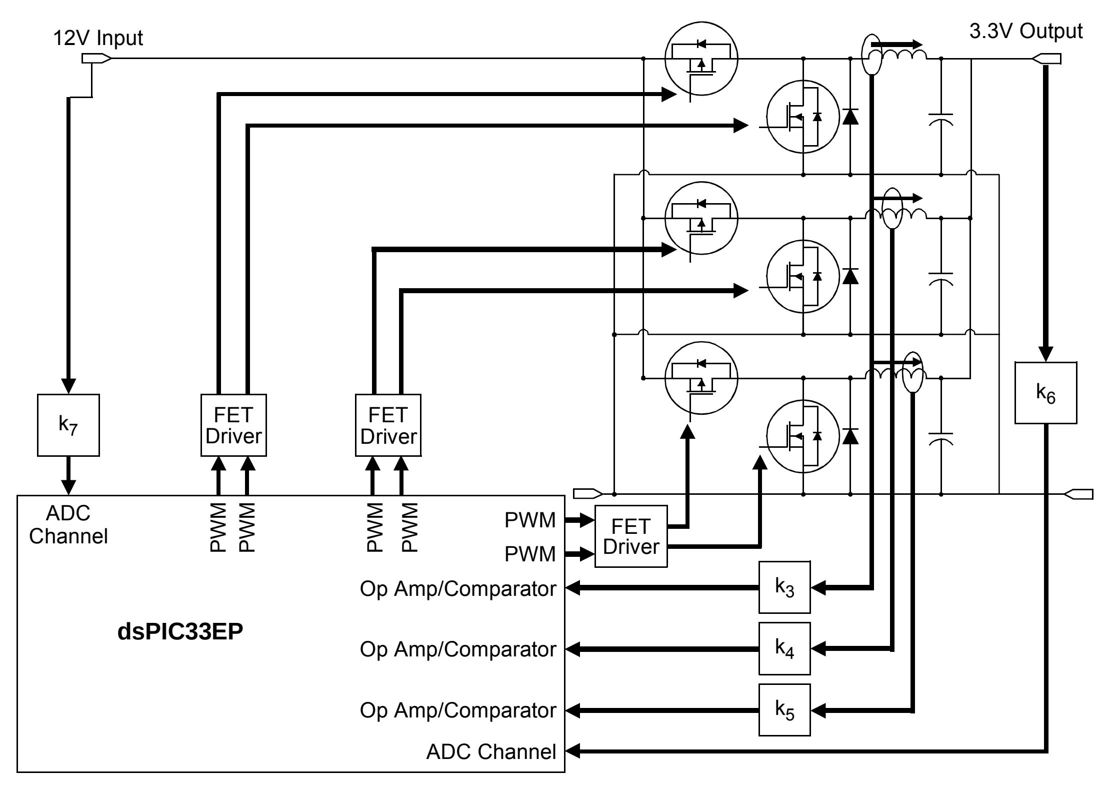


FIGURE 2-6: MULTIPHASE SYNCHRONOUS BUCK CONVERTER



REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5	**IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3) `111` = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled `110` = CPU Interrupt Priority Level is 6 (14) `101` = CPU Interrupt Priority Level is 5 (13) `100` = CPU Interrupt Priority Level is 4 (12) `011` = CPU Interrupt Priority Level is 3 (11) `010` = CPU Interrupt Priority Level is 2 (10) `001` = CPU Interrupt Priority Level is 1 (9) `000` = CPU Interrupt Priority Level is 0 (8)
bit 4	**RA:** REPEAT Loop Active bit `1` = REPEAT loop in progress `0` = REPEAT loop not in progress
bit 3	**N:** MCU ALU Negative bit `1` = Result was negative `0` = Result was non-negative (zero or positive)
bit 2	**OV:** MCU ALU Overflow bit This bit is used for signed arithmetic (2’s complement). It indicates an overflow of the magnitude that causes the sign bit to change state. `1` = Overflow occurred for signed arithmetic (in this arithmetic operation) `0` = No overflow occurred
bit 1	**Z:** MCU ALU Zero bit `1` = An operation that affects the Z bit has set it at some time in the past `0` = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)
bit 0	**C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit `1` = A carry-out from the Most Significant bit of the result occurred `0` = No carry-out from the Most Significant bit of the result occurred

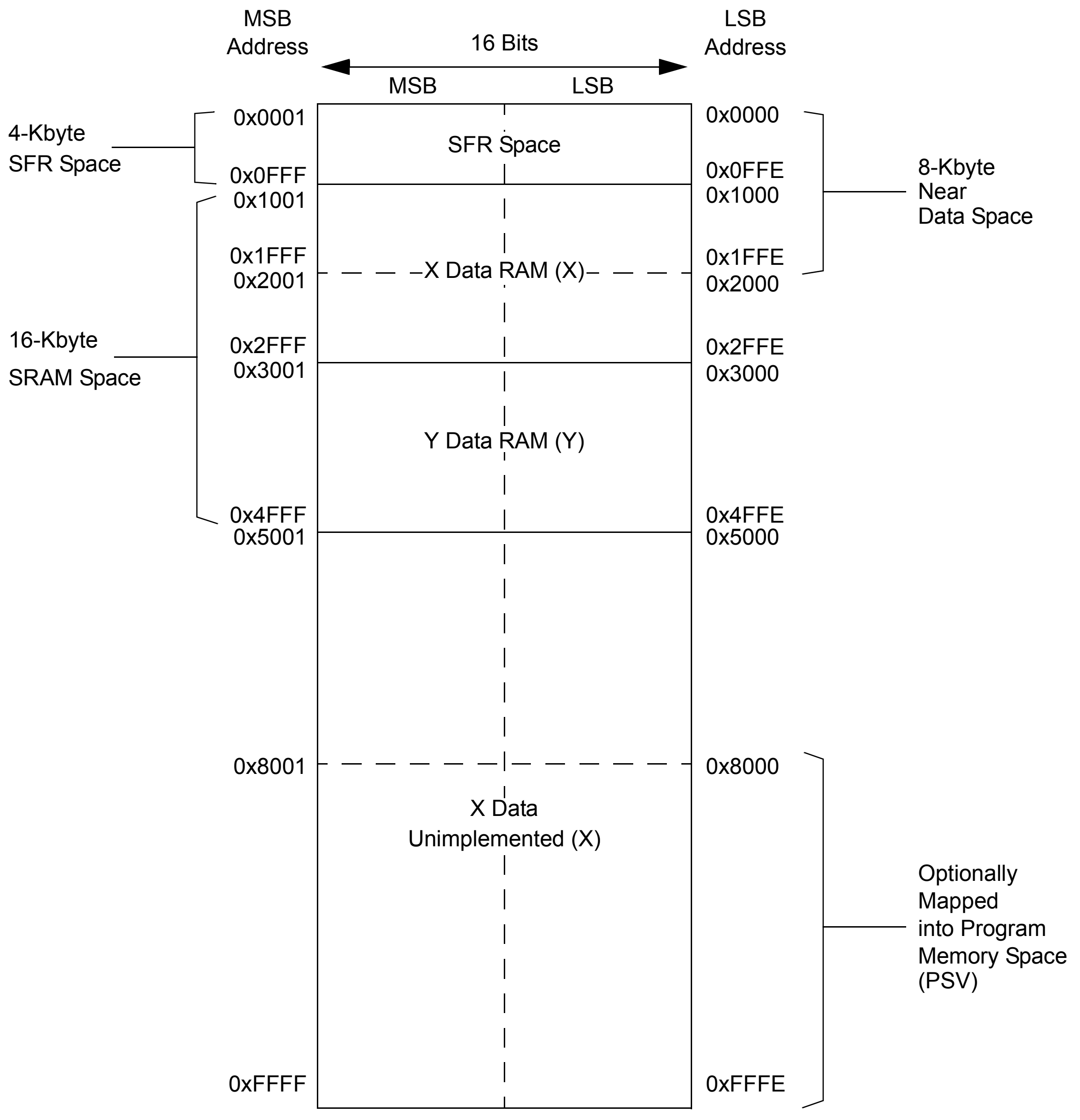
Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = `1`. User interrupts are disabled when IPL<3> = `1`.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = `1`.

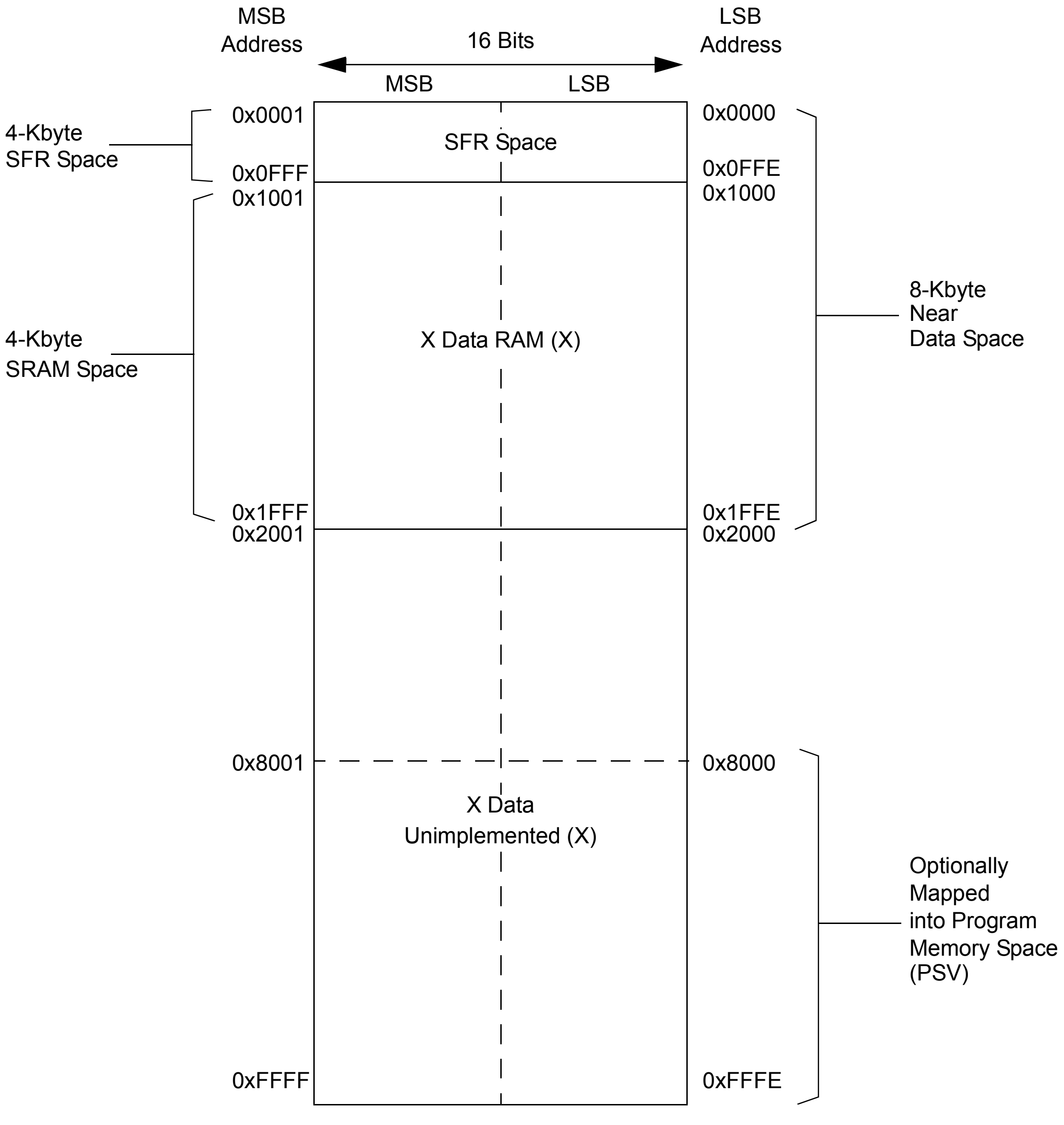
4: A data write to the SR register can modify the SA and SB bits by either a data write to SA and SB or by clearing the SAB bit. To avoid a possible SA or SB bit write race condition, the SA and SB bits should not be modified using bit operations.

FIGURE 4-9: DATA MEMORY MAP FOR dsPIC33EP128MC20X/50X AND dsPIC33EP128GP50X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 4-12: DATA MEMORY MAP FOR PIC24EP32GP/MC20X/50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-45: DMAC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA0STAL	0B04	STA<15:0>																0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA0STBL	0B08	STB<15:0>																0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA0PAD	0B0C	PAD<15:0>																0000
DMA0CNT	0B0E	—	—	CNT<13:0>														0000
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA1STAL	0B14	STA<15:0>																0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA1STBL	0B18	STB<15:0>																0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA1PAD	0B1C	PAD<15:0>																0000
DMA1CNT	0B1E	—	—	CNT<13:0>														0000
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA2STAL	0B24	STA<15:0>																0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA2STBL	0B28	STB<15:0>																0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA2PAD	0B2C	PAD<15:0>																0000
DMA2CNT	0B2E	—	—	CNT<13:0>														0000
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA3STAL	0B34	STA<15:0>																0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA3STBL	0B38	STB<15:0>																0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA3PAD	0B3C	PAD<15:0>																0000
DMA3CNT	0B3E	—	—	CNT<13:0>														0000
DMAPWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000
DMARQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000
DMAPPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000
DMALCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F
DSADRL	0BF8	DSADR<15:0>																0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER[1] (CONTINUED)

bit 4	**Unimplemented:** Read as '`0`'
bit 3	**CF:** Clock Fail Detect bit[3] `1` = FSCM has detected clock failure `0` = FSCM has not detected clock failure
bit 2-1	**Unimplemented:** Read as '`0`'
bit 0	**OSWEN:** Oscillator Switch Enable bit `1` = Requests oscillator switch to selection specified by the NOSC<2:0> bits `0` = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"* (available from the Microchip web site) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This bit should only be cleared in software. Setting the bit in software (= `1`) will have the same effect as an actual oscillator failure and trigger an oscillator failure trap.

REGISTER 11-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	IC1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘`0`’
bit 14-8	**IC2R<6:0>:** Assign Input Capture 2 (IC2) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS
bit 7	**Unimplemented:** Read as ‘`0`’
bit 6-0	**IC1R<6:0>:** Assign Input Capture 1 (IC1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to VSS

REGISTER 11-7: RPINR12: PERIPHERAL PIN SELECT INPUT REGISTER 12 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT2R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	FLT1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘`0`’

bit 14-8 **FLT2R<6:0>:** Assign PWM Fault 2 (FLT2) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

bit 7 **Unimplemented:** Read as ‘`0`’

bit 6-0 **FLT1R<6:0>:** Assign PWM Fault 1 (FLT1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 11-10: RPINR18: PERIPHERAL PIN SELECT INPUT REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7	**Unimplemented:** Read as ‘`0`’
bit 6-0	**U1RXR<6:0>:** Assign UART1 Receive (U1RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to V_{SS}

REGISTER 11-11: RPINR19: PERIPHERAL PIN SELECT INPUT REGISTER 19

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U2RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7	**Unimplemented:** Read as ‘`0`’
bit 6-0	**U2RXR<6:0>:** Assign UART2 Receive (U2RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers) `1111001` = Input tied to RPI121 . . . `0000001` = Input tied to CMP1 `0000000` = Input tied to V_{SS}

NOTES:

21.2 Modes of Operation

The ECAN module can operate in one of several operation modes selected by the user. These modes include:

- Initialization mode
- Disable mode
- Normal Operation mode
- Listen Only mode
- Listen All Messages mode
- Loopback mode

Modes are requested by setting the REQOP<2:0> bits (CxCTRL1<10:8>). Entry into a mode is Acknowledged by monitoring the OPMODE<2:0> bits (CxCTRL1<7:5>). The module does not change the mode and the OPMODEx bits until a change in mode is acceptable, generally during bus Idle time, which is defined as at least 11 consecutive recessive bits.

21.3 ECAN Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

21.3.1 KEY RESOURCES

- **“Enhanced Controller Area Network (ECAN™)”** (DS70353) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

24.2 PTG Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

24.2.1 KEY RESOURCES

- **"Peripheral Trigger Generator"** (DS70669) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OAANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**HLMS:** High or Low-Level Masking Select bits `1` = The masking (blanking) function will prevent any asserted (‘`0`’) comparator signal from propagating `0` = The masking (blanking) function will prevent any asserted (‘`1`’) comparator signal from propagating
bit 14	**Unimplemented:** Read as ‘`0`’
bit 13	**OCEN:** OR Gate C Input Enable bit `1` = MCI is connected to OR gate `0` = MCI is not connected to OR gate
bit 12	**OCNEN:** OR Gate C Input Inverted Enable bit `1` = Inverted MCI is connected to OR gate `0` = Inverted MCI is not connected to OR gate
bit 11	**OBEN:** OR Gate B Input Enable bit `1` = MBI is connected to OR gate `0` = MBI is not connected to OR gate
bit 10	**OBNEN:** OR Gate B Input Inverted Enable bit `1` = Inverted MBI is connected to OR gate `0` = Inverted MBI is not connected to OR gate
bit 9	**OAEN:** OR Gate A Input Enable bit `1` = MAI is connected to OR gate `0` = MAI is not connected to OR gate
bit 8	**OANEN:** OR Gate A Input Inverted Enable bit `1` = Inverted MAI is connected to OR gate `0` = Inverted MAI is not connected to OR gate
bit 7	**NAGS:** AND Gate Output Inverted Enable bit `1` = Inverted ANDI is connected to OR gate `0` = Inverted ANDI is not connected to OR gate
bit 6	**PAGS:** AND Gate Output Enable bit `1` = ANDI is connected to OR gate `0` = ANDI is not connected to OR gate
bit 5	**ACEN:** AND Gate C Input Enable bit `1` = MCI is connected to AND gate `0` = MCI is not connected to AND gate
bit 4	**ACNEN:** AND Gate C Input Inverted Enable bit `1` = Inverted MCI is connected to AND gate `0` = Inverted MCI is not connected to AND gate

28.0 INSTRUCTION SET SUMMARY

> **Note:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33EP instruction set is almost identical to that of the dsPIC30F and dsPIC33F. The PIC24EP instruction set is almost identical to that of the PIC24F and PIC24H.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 28-1 lists the general symbols used in describing the instructions.

The dsPIC33E instruction set summary in Table 28-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The `MAC` class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write back destination

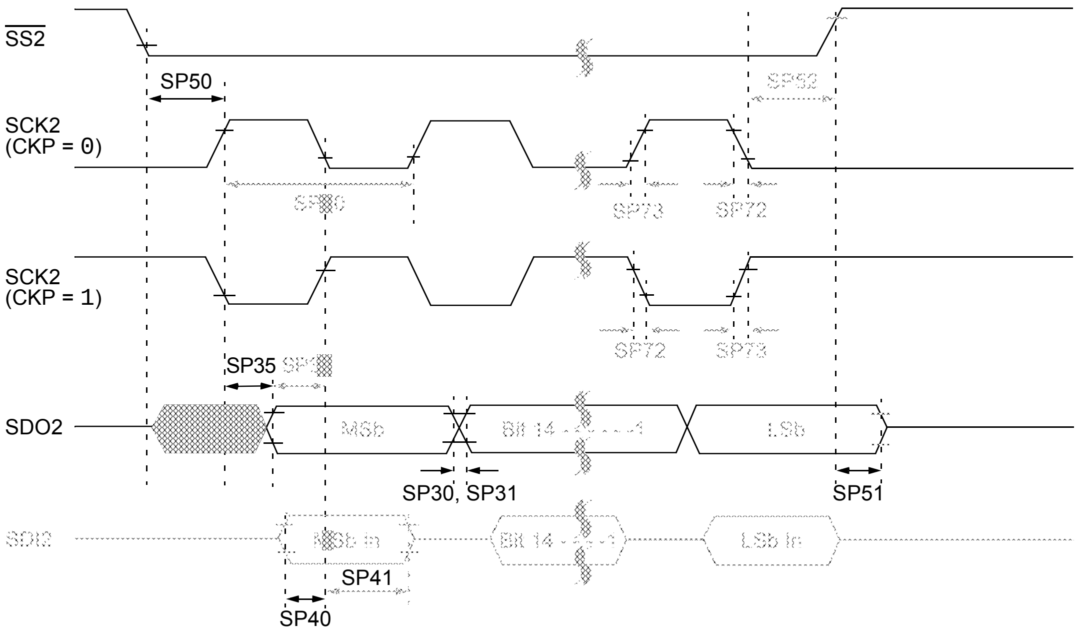
The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the Table Read and Table Write instructions

FIGURE 30-21: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



[redacted]

31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 “Electrical Characteristics”** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 “Electrical Characteristics”** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2)	-40°C to +150°C
Storage temperature	-65°C to +160°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(3)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD < 3.0V(3)	-0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3)	-0.3V to 5.5V
Maximum current out of VSS pin	60 mA
Maximum current into VDD pin(4)	60 mA
Maximum junction temperature	+155°C
Maximum current sourced/sunk by any 4x I/O pin	10 mA
Maximum current sourced/sunk by any 8x I/O pin	15 mA
Maximum current sunk by all ports combined	70 mA
Maximum current sourced by all ports combined(4)	70 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Refer to the **“Pin Diagrams”** section for 5V tolerant pins.

4: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})						
HDC60e	1400	2500	μA	+150°C	3.3V	Base Power-Down Current **(Notes 1, 3)**
HDC61c	15	—	μA	+150°C	3.3V	Watchdog Timer Current: ΔI_{WDT} **(Notes 2, 4)**

Note 1: Base I_{PD} is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to V_{SS}. WDT, etc., are all switched off and VREGS (RCON<8>) = `1`.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 31-5: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC44e	12	30	mA	+150°C	3.3V	40 MIPS

TABLE 31-6: DC CHARACTERISTICS: OPERATING CURRENT (I_{DD})

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
HDC20	9	15	mA	+150°C	3.3V	10 MIPS
HDC22	16	25	mA	+150°C	3.3V	20 MIPS
HDC23	30	50	mA	+150°C	3.3V	40 MIPS

TABLE 31-7: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +150°C				
Parameter No.	**Typical**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	24	35	1:2	mA	+150°C	3.3V	40 MIPS
HDC72f(1)	14	—	1:64	mA			
HDC72g(1)	12	—	1:128	mA			

Note 1: Parameters with Doze ratios of 1:64 and 1:128 are characterized, but are not tested in manufacturing.